

Abstract of the Disclosure

A polishing pad, a polishing laminated pad and a semiconductor wafer polishing method all of which prevent a leak of slurry from the gap between a polishing substrate and a reduction in polishing efficiency caused by a scratched and a window member and enable the optical detection of the polishing end point to be carried out efficiently.

The polishing pad comprises a polishing substrate having a through hole extending from the front side to the rear side and a light transmitting member arranged in the through hole, and the outer wall of the above light transmitting member and the inner wall of the through hole opposite to the outer wall are bonded together with a photocurable adhesive such as a polyurethane (meth)acrylate to fix the above light transmitting member in the through hole.